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2823  
#13/Amend B  
PATENT  
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TECHNOLOGY CENTER-2800  
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RECEIVED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sailish Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS  
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents  
Washington, D.C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 2-14-2002 (date)

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Elizabeth Schumacher  
(Signature of the person signing the certificate)

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Office Action mailed December 21, 2001, please amend the above-identified Application as follows:

IN THE CLAIMS:

Please amend Claim 1 as follows:

1. (Amended) A wire bonding method, comprising the steps of:  
forming a semiconductor substrate with a copper (Cu) interconnect material;

B1 sub C1